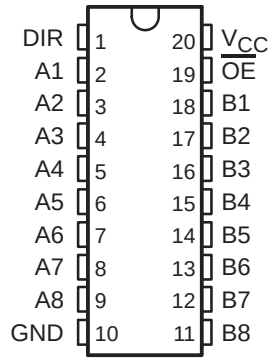
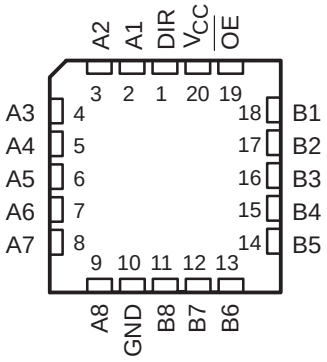
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical $V_{OLP}$ (Output Ground Bounce) < 1 V at $V_{CC}$ = 5 V, $T_A$ = 25°C**
- **High-Drive Outputs (–32-mA $I_{OH}$, 64-mA $I_{OL}$)**
- **Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs**

**SN54ABT245 . . . J PACKAGE**
**SN74ABT245 . . . DB, DW, OR N PACKAGE**
**(TOP VIEW)**




**SN54ABT245 . . . FK PACKAGE**
**(TOP VIEW)**




## description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to $V_{CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT245 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT245 is characterized for operation from –40°C to 85°C.

**FUNCTION TABLE**

| INPUTS | | OPERATION |
|---|---|---|
| $\overline{OE}$ | DIR | |
| L | L | B data to A bus |
| L | H | A data to B bus |
| H | X | Isolation |

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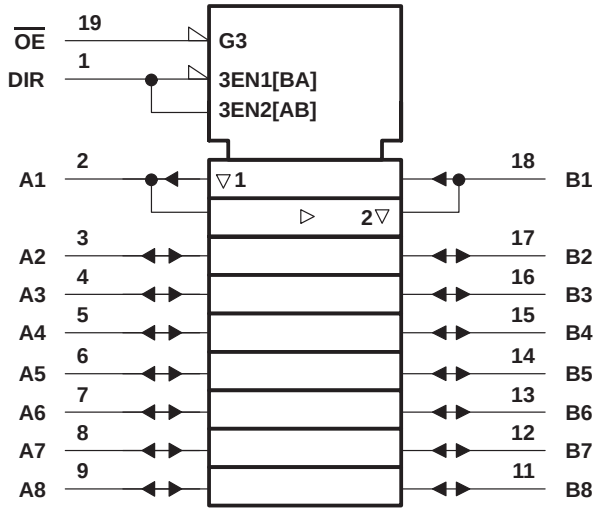
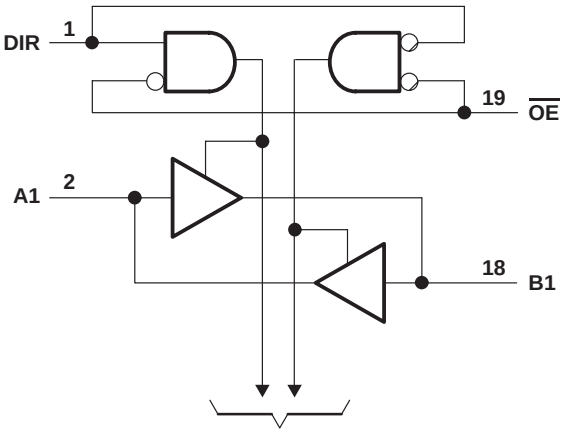
### logic symbol†




### logic diagram (positive logic)




† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ . . . . . –0.5 V to 7 V
Input voltage range, $V_I$ (except I/O ports) (see Note 1) . . . . . –0.5 V to 7 V
Voltage applied to any output in the high state or power-off state, $V_O$ . . . . . –0.5 V to 5.5 V
Current into any output in the low state, $I_O$: SN54ABT245 . . . . . 96 mA
SN74ABT245 . . . . . 128 mA
Input clamp current, $I_{IK}$ ($V_I$ < 0) . . . . . –18 mA
Output clamp current, $I_{OK}$ ($V_O$ < 0) . . . . . –50 mA
Maximum power dissipation at $T_A$ = 55°C (in still air) (see Note 2): DB package . . . . . 0.6 W
DW package . . . . . 1.6 W
N package . . . . . 1.3 W
Storage temperature range . . . . . –65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

## recommended operating conditions (see Note 3)

| | | SN54ABT245 | | SN74ABT245 | | UNIT |
|---|---|---|---|---|---|---|
| | | MIN | MAX | MIN | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| $V_{IH}$ | High-level input voltage | 2 | | 2 | | V |
| $V_{IL}$ | Low-level input voltage | | 0.8 | | 0.8 | V |
| $V_I$ | Input voltage | 0 | $V_{CC}$ | 0 | $V_{CC}$ | V |
| $I_{OH}$ | High-level output current | | –24 | | –32 | mA |
| $I_{OL}$ | Low-level output current | | 48 | | 64 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | 5 | | 5 | ns/V |
| $T_A$ | Operating free-air temperature | –55 | 125 | –40 | 85 | °C |

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | | $T_A$ = 25°C | | | SN54ABT245 | | SN74ABT245 | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP† | MAX | MIN | MAX | MIN | MAX | |
| $V_{IK}$ | $V_{CC}$ = 4.5 V, | $I_I$ = –18 mA | | | | –1.2 | | –1.2 | | –1.2 | V |
| $V_{OH}$ | $V_{CC}$ = 4.5 V, | $I_{OH}$ = – 3 mA | | 2.5 | | | 2.5 | | 2.5 | | V |
| | $V_{CC}$ = 5 V, | $I_{OH}$ = – 3 mA | | 3 | | | 3 | | 3 | | |
| | $V_{CC}$ = 4.5 V | $I_{OH}$ = – 24 mA | | 2 | | | 2 | | | | |
| | | $I_{OH}$ = – 32 mA | | 2* | | | | | 2 | | |
| $V_{OL}$ | $V_{CC}$ = 4.5 V | $I_{OL}$ = 48 mA | | | | 0.55 | | 0.55 | | | V |
| | | $I_{OL}$ = 64 mA | | | | 0.55* | | | | 0.55 | |
| $I_I$ | $V_{CC}$ = 5.5 V, $V_I$ = $V_{CC}$ or GND | | Control inputs | | | ±1 | | ±1 | | ±1 | µA |
| | | | A or B ports | | | ±100 | | ±100 | | ±100 | |
| $I_{OZH}$‡ | $V_{CC}$ = 5.5 V, | $V_O$ = 2.7 V | | | | 10§ | | 10§ | | 10§ | µA |
| $I_{OZL}$‡ | $V_{CC}$ = 5.5 V, | $V_O$ = 0.5 V | | | | –10§ | | –10§ | | –10§ | µA |
| $I_{off}$ | $V_{CC}$ = 0, | $V_I$ or $V_O \le$ 4.5 V | | | | ±100 | | | | ±100 | µA |
| $I_{CEX}$ | $V_{CC}$ = 5.5 V, | $V_O$ = 5.5 V | Outputs high | | | 50 | | 50 | | 50 | µA |
| $I_O$¶ | $V_{CC}$ = 5.5 V, | $V_O$ = 2.5 V | | –50 | –140 | –180 | –50 | –180 | –50 | –180 | mA |
| $I_{CC}$ | $V_{CC}$ = 5.5 V, $I_O$ = 0, $V_I$ = $V_{CC}$ or GND | A or B ports | Outputs high | | 5 | 250 | | 250 | | 250 | µA |
| | | | Outputs low | | 22 | 30 | | 30 | | 30 | mA |
| | | | Outputs disabled | | 1 | 250 | | 250 | | 250 | µA |
| $\Delta I_{CC}$# | $V_{CC}$ = 5.5 V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND | Data inputs | Outputs enabled | | | 1.5 | | 1.5 | | 1.5 | mA |
| | | | Outputs disabled | | | 50 | | 50 | | 50 | µA |
| | | Control inputs | | | | 1.5 | | 1.5 | | 1.5 | mA |
| $C_i$ | $V_I$ = 2.5 V or 0.5 V | | Control inputs | | 4 | | | | | | pF |
| $C_{io}$ | $V_O$ = 2.5 V or 0.5 V | | A or B ports | | 8 | | | | | | pF |

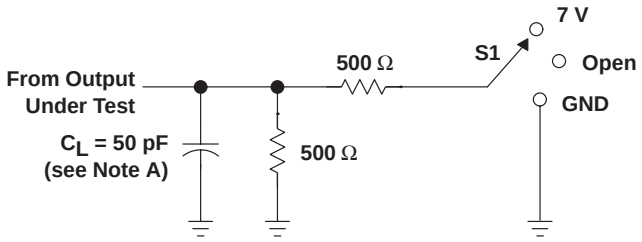
* On products compliant to MIL-STD-883, Class B, this parameter does not apply.
† All typical values are at $V_{CC}$ = 5 V.
‡ The parameters $I_{OZH}$ and $I_{OZL}$ include the input leakage current.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{CC}$ or GND.

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)**

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ = 5 V, $T_A$ = 25°C | | | SN54ABT245 | | SN74ABT245 | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| $t_{PLH}$ | A or B | B or A | 1 | 2.6 | 4.1 | 1 | 4.8 | 1 | 4.6 | ns |
| $t_{PHL}$ | | | 1 | 2.9 | 4.2 | 1 | 4.8 | 1 | 4.6 | |
| $t_{PZH}$ | $\overline{OE}$ | A or B | 1.3 | 3.3 | 4.8 | 1 | 5.9 | 1.3 | 5.3 | ns |
| $t_{PZL}$ | | | 2.3 | 4.3 | 5.8 | 2 | 7.5 | 2.3 | 6.3 | |
| $t_{PHZ}$ | $\overline{OE}$ | A or B | 1.7† | 4.7 | 6.2 | 1.7 | 7.4 | 1.7† | 7.2 | ns |
| $t_{PLZ}$ | | | 1.7† | 4.3 | 5.8 | 1.7 | 6.5 | 1.7† | 6.3 | |

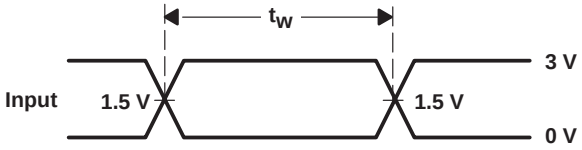
† This data sheet limit may vary among suppliers.

## PARAMETER MEASUREMENT INFORMATION

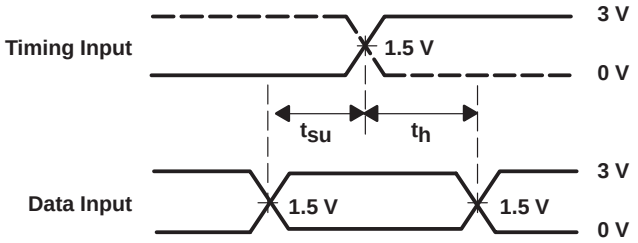



| TEST | S1 |
|---|---|
| $t_{PLH}/t_{PHL}$ | Open |
| $t_{PLZ}/t_{PZL}$ | 7 V |
| $t_{PHZ}/t_{PZH}$ | Open |

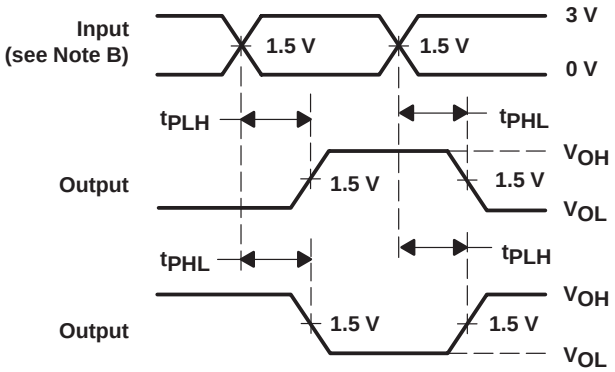
LOAD CIRCUIT FOR OUTPUTS



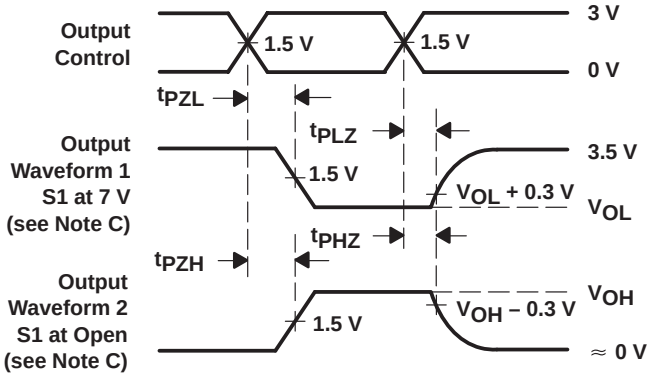

VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. $C_L$ includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O$ = 50 Ω, $t_r$ ≤ 2.5 ns, $t_f$ ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

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